

# SOT1148-1

HBGA404, plastic thermal enhanced ball grid array; 404 balls;  
1 mm pitch, 23 mm x 23 mm x 1.75 mm body

14 June 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HBGA404
<b>Package type industry code</b>	HBGA404
<b>Package style descriptive code</b>	HBGA (thermal enhanced ball grid array)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	144E
<b>JEDEC package outline code</b>	MS-034
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-6-2017
<b>Manufacturer package code</b>	SOT1148

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	22.8	-	23	23.2	mm
E	package width	22.8	-	23	23.2	mm
A	seated height	-	-	-	-	mm
A <sub>2</sub>	package height	1.6	-	1.75	1.85	mm
e	nominal pitch	-	-	1	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	404	-	



HBGA404, plastic thermal enhanced ball grid array; 404 balls; 1 mm pitch, 23 mm x 23 mm x 1.75 mm body

## 2. Package outline

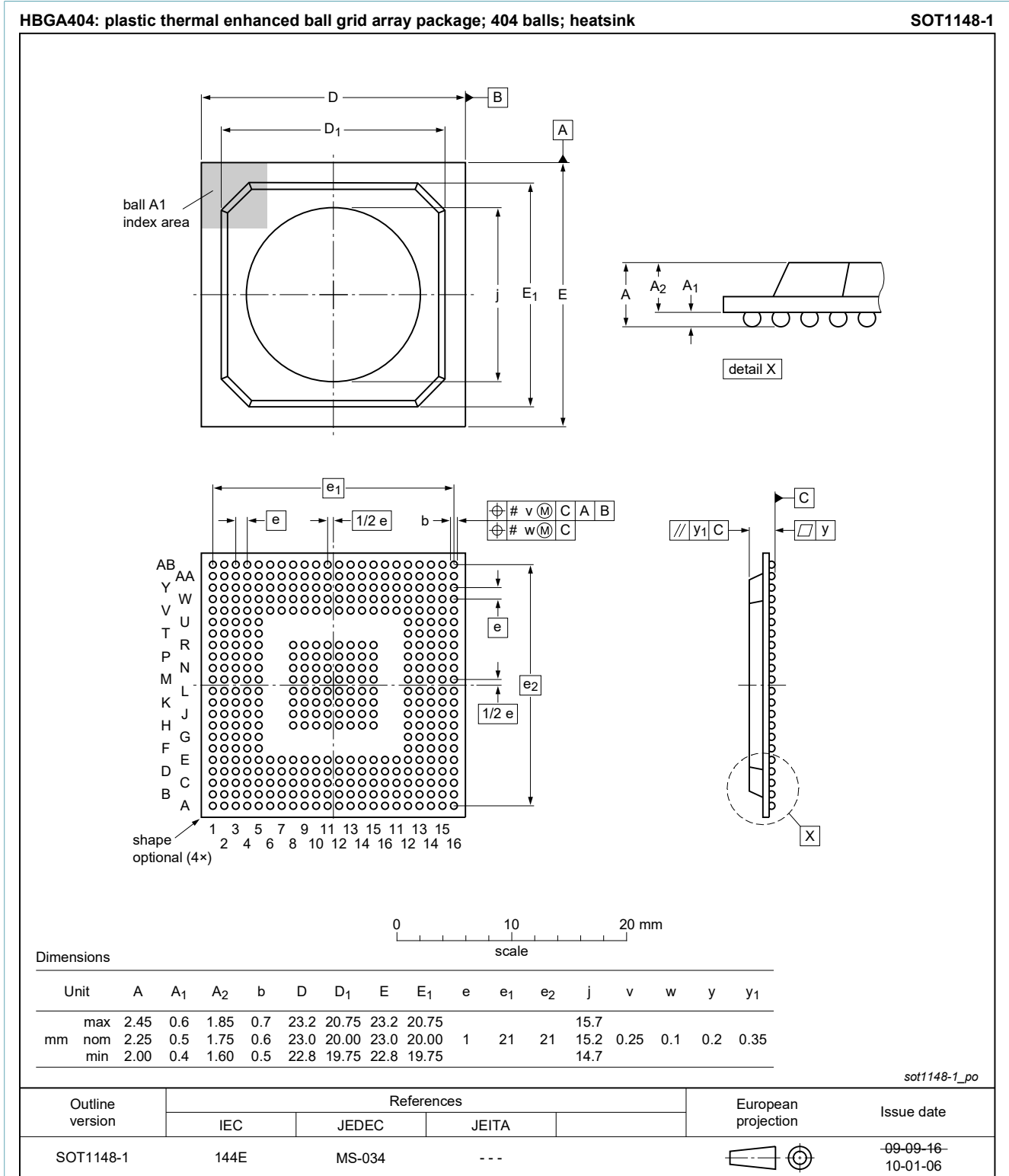


Fig. 1. Package outline HBGA404 (SOT1148-1)

### 3. Legal information

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